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STT-MRAM For Radiation Hard Environments

Sanjeev Aggarwal

Everspin: MRAM Technology Pioneer

Everspin is a Leading Provider of Non-volatile Memory Technology and Products to Mission-Critical **Data Center, Industrial** and **Auto/Transportation** Applications

- Origins in Motorola/Freescale
- Independent since 2008
- Publicly traded : MRAM
- Long-served tier-1 customers

600+

Customers across many markets

110M+

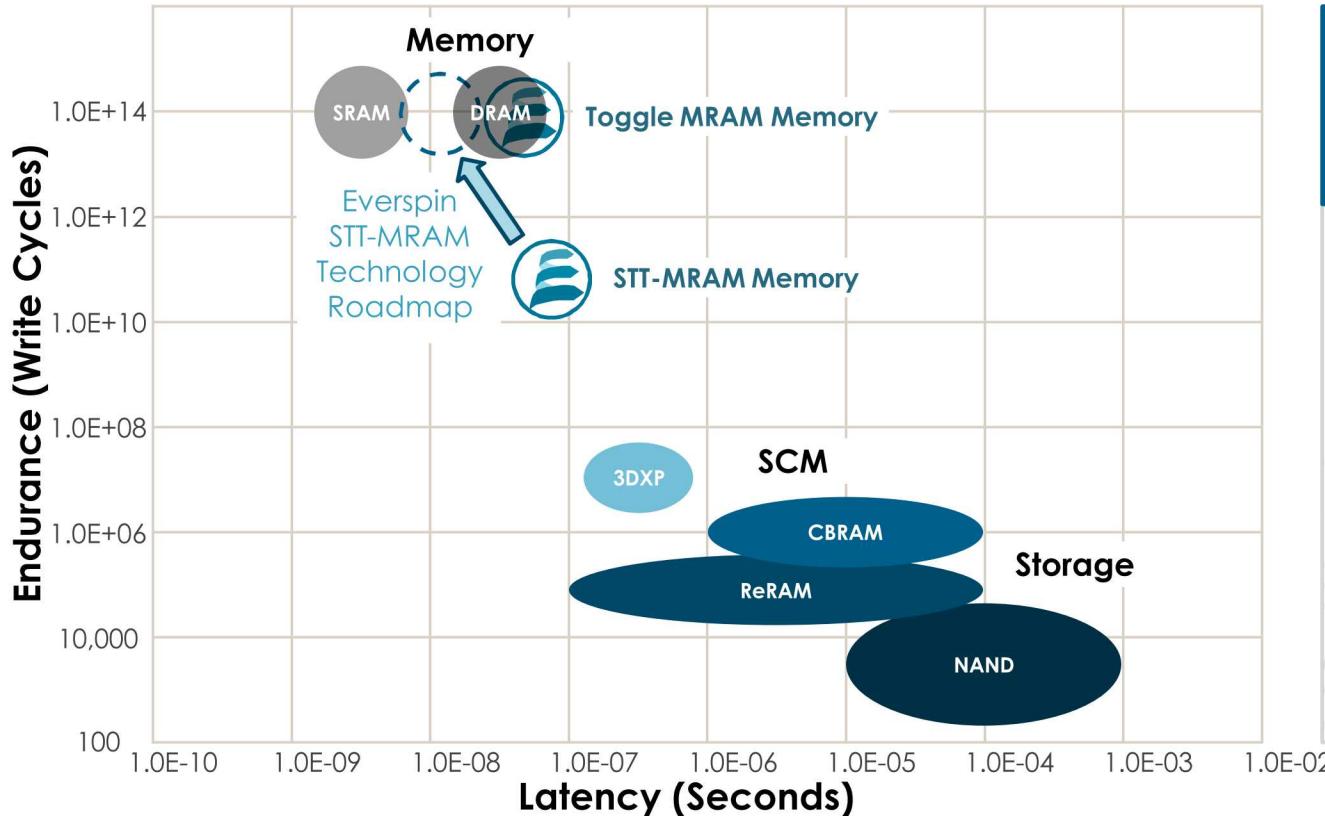
Units shipped

600+

Patents and applications WW

Our products bring the unique benefits of MRAM to our customers where Performance, Persistence, Endurance and Reliability are critical

MRAM Brings Native Persistence to Memory Workloads



**MRAM COMBINES
PERFORMANCE OF MEMORY
WITH PERSISTENCE
OF STORAGE**

- **Non-Volatile:** Maintains data without power or refresh
- **Fast:** Read/write similar to DRAM
- **Endurance:** Handles memory workloads

Data Center OEM Qualifies Everspin's 1Gb STT-MRAM Solution

BusinessWire
A Berkshire Hathaway Company

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Everspin Achieves Data Center OEM qualification of its 1Gb STT-MRAM Solution

With this customer design win qualification, Everspin also announces production shipments of the 1Gb STT-MRAM



The Data Center OEM name is not being disclosed as they have not yet announced their end product(s).

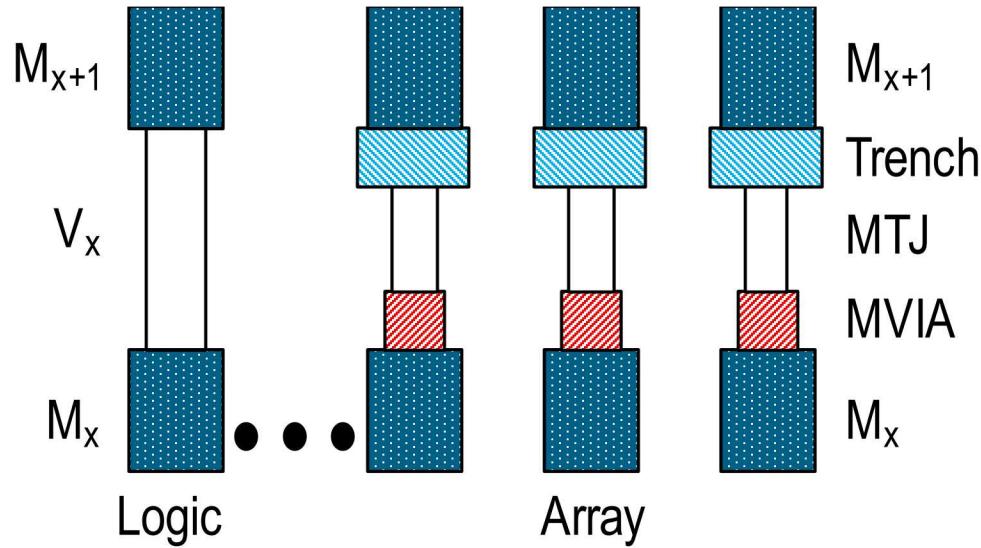
Everspin's 1 Gb STT-MRAM Component (Photo: Business Wire)

December 11, 2019 08:00 AM Eastern Standard Time

<https://www.businesswire.com/news/home/20191211005184/en/Everspin-Achieves-Data-Center-OEM-qualification-1Gb>

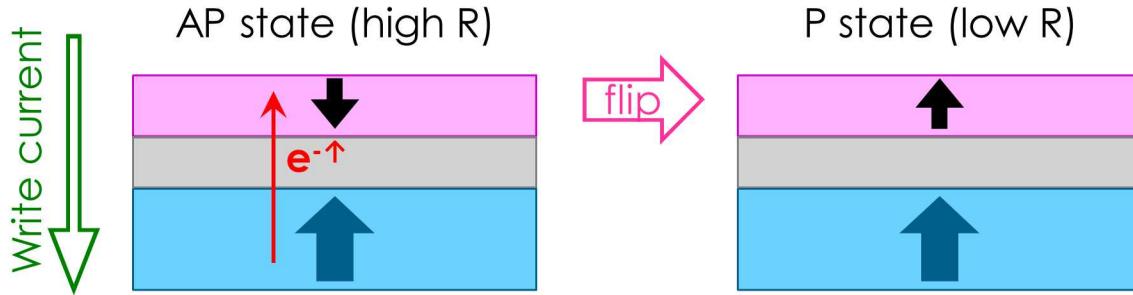
STT-MRAM – Easy to Integrate with Standard CMOS

On Axis Integration, 1Gb

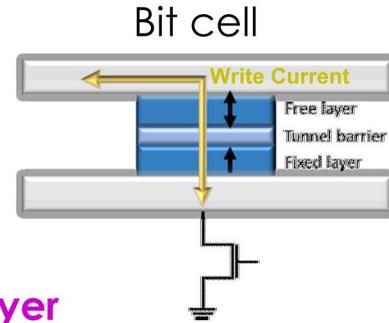
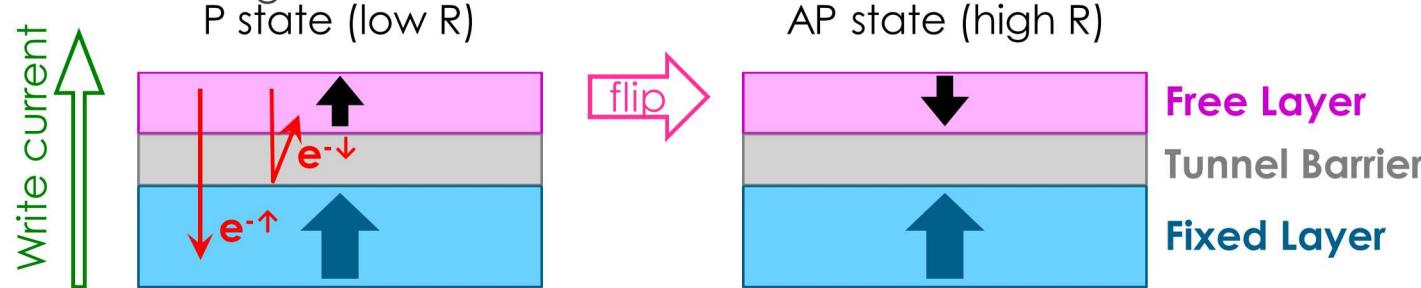


Spin-Transfer Torque (STT) Switching

- AP to P switching



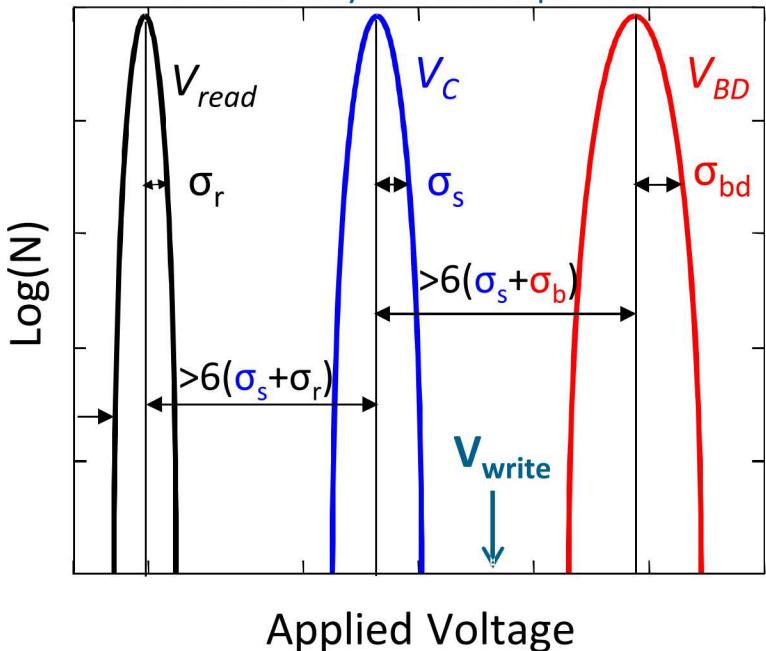
- P to AP switching



Must separate bit-to-bit distributions in the array

Separation of distributions is key for working memory

MB memory $\Rightarrow >12\sigma$ separation



- Separation of V_C & V_{BD}

- V_{write} must be well above V_C and well below V_{BD}
- Tight switching distributions
- Tunnel barrier reliability

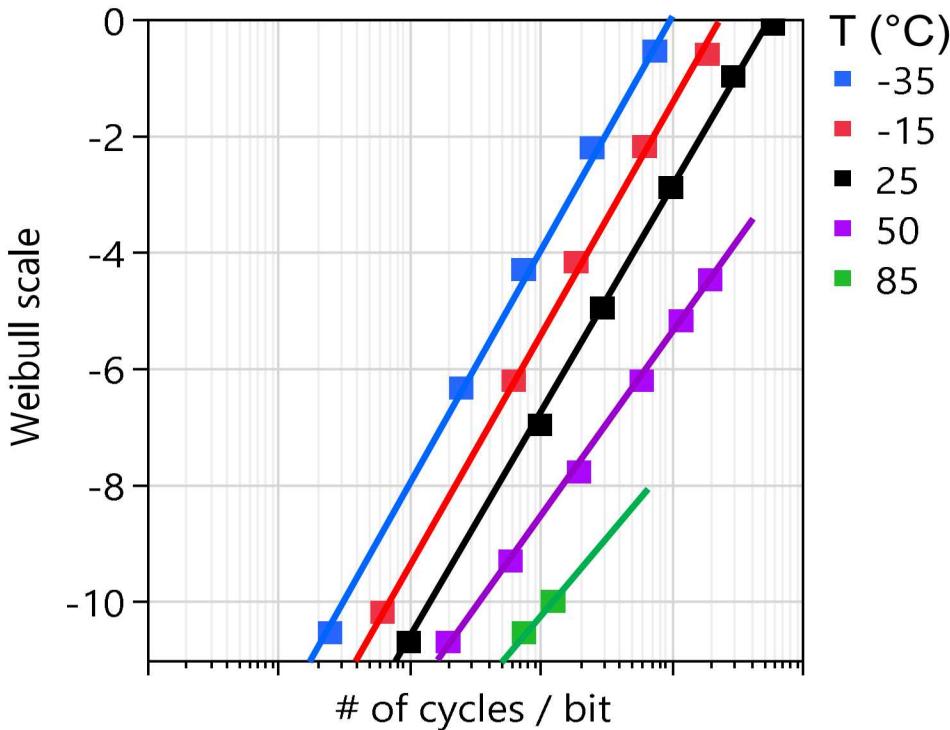
- Separation of V_{read} & V_C

- Avoid read-disturb errors
- Bigger issue for smaller bits, lower I_C

- Separation gets worse with:

- Shorter write pulses
- Smaller bits
- Extrinsic switching or breakdown behavior

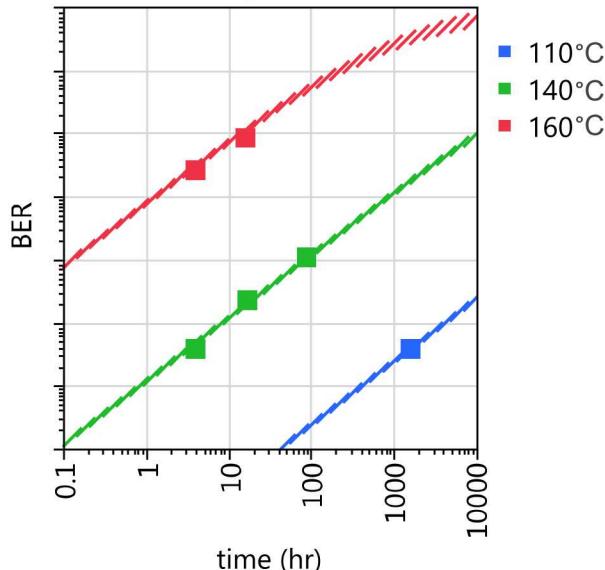
1Gb STT-MRAM Endurance across Temperature



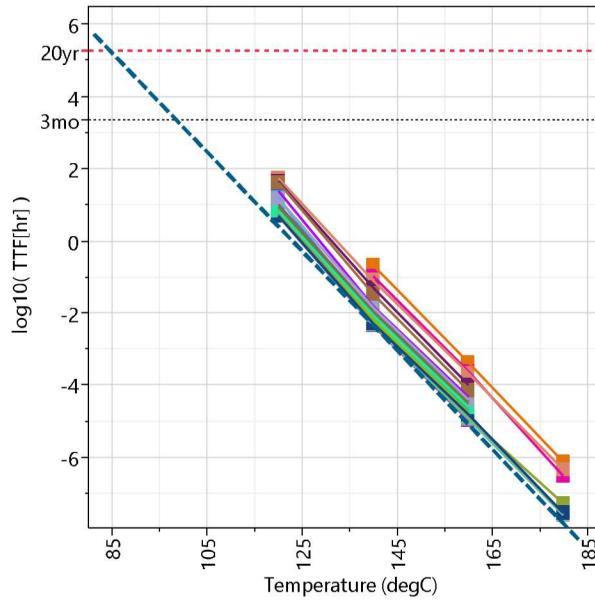
- TDDB BER with ECC off vs. cycles shows linear breakdown distributions from -35°C to 85°C
 - Weibull plot at different temperature are horizontally offset for clarity
- No indication of a deviation due to early breakdown of extrinsic defect bit observed
- The TDDB beta parameter is relatively similar across the temperature range

Extended Temperature Range: Data retention for 1Gb STT-MRAM

Example die



Projected Data Retention



- Baked typical die over 110 – 160 °C for 1hr to 9 weeks
- Fitted to project data retention; Time-to-failure (TTF) is extracted from the fit

STT-MRAM Radiation Hard Testing

Everspin Technologies Contributors

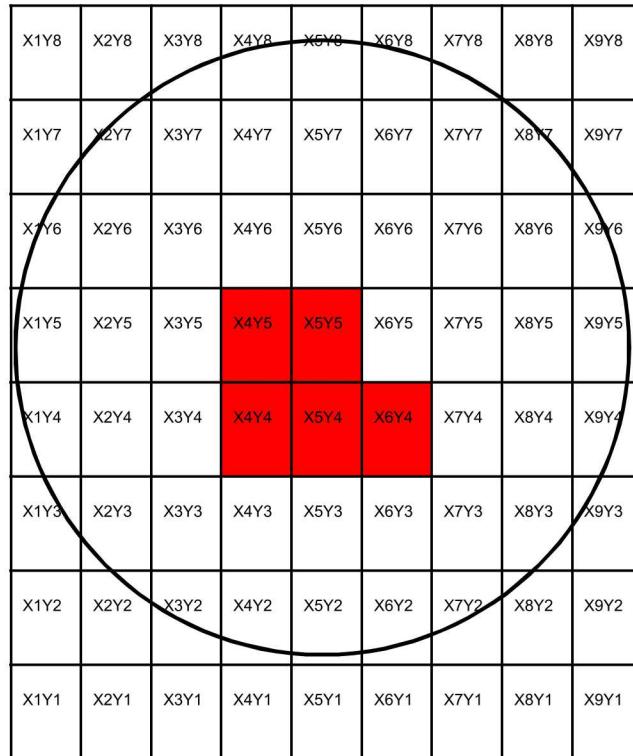
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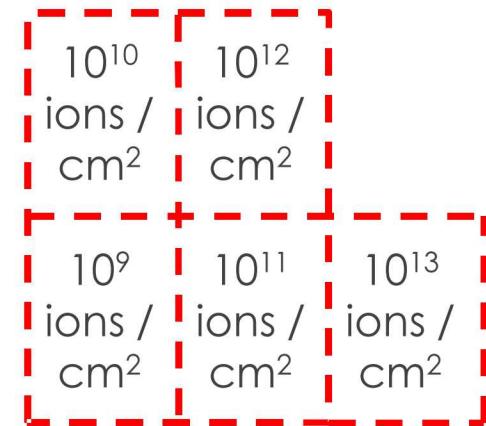
Marinella, Matthew
Manuel, Jack E
Bielejec, Edward S
Jacobs-Gedrim, Robin B
Xiao, Tianyao
Hughart, David
Arghavani, Reza
Bennett, Christopher
Buchheit, Thomas

Heavy Ion Exposure Map

- MTJs have metallic top/bottom electrodes, but no CMOS transistors
- 5 reticle shots at wafer center exposed to heavy ions
- Doses varied from 10^9 to 10^{13} ions/cm²
- Remaining reticle shots served as unexposed control MTJs

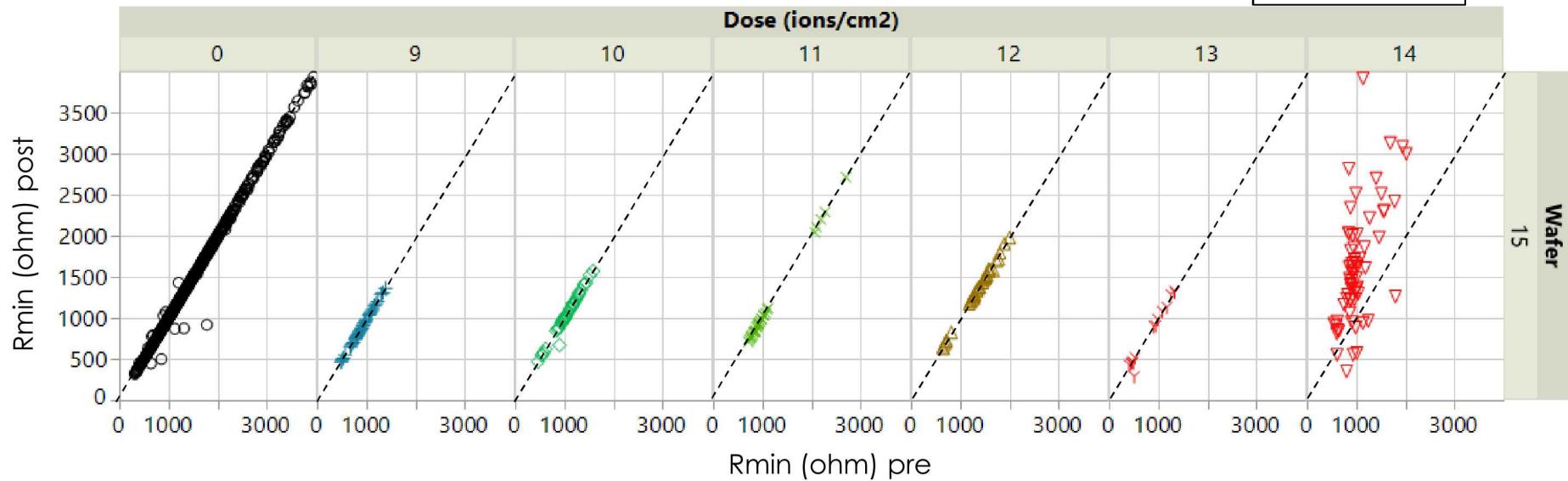


5 exposed
reticle shots



Rmin: Post vs. Pre-Exposure (Single MTJ Structures)

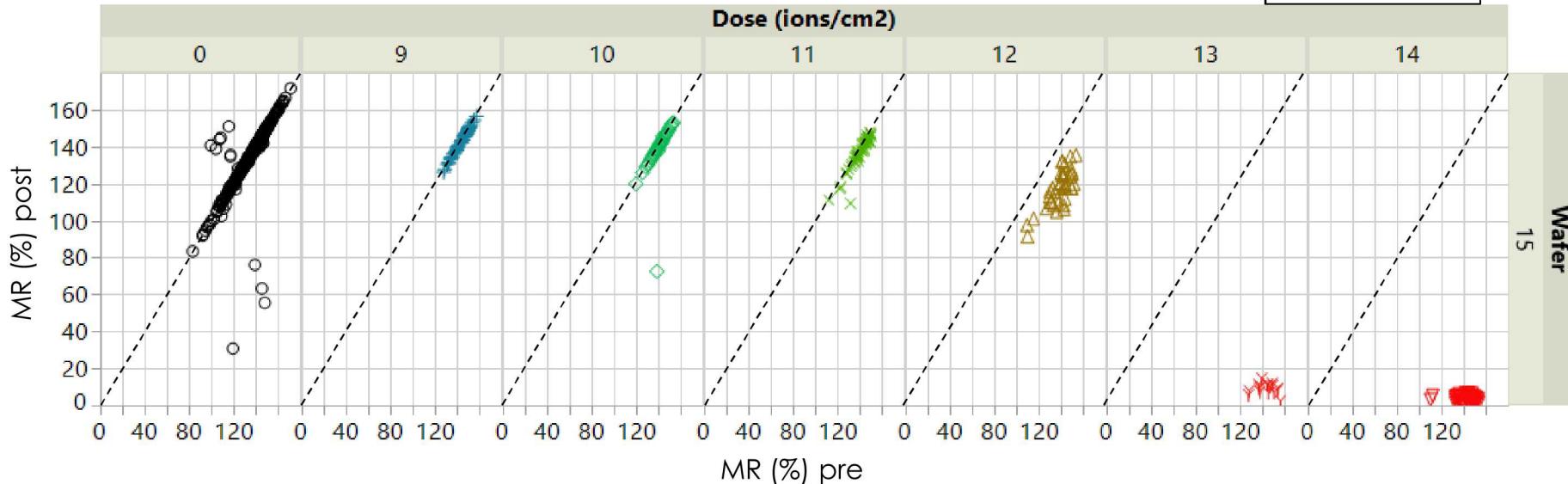
Short flow
1 point = 1 bit



- Exact same MTJs were measured after exposure (y-axis) vs. before exposure (x-axis)
- Increasing dose is plotted left to right starting at dose = 0 (unexposed reticle shots)
- Rmin remains unchanged by exposure up to 10^{13} ions/cm²
 - However, 10^{13} ions/cm² shows significant magnetic change to MTJ: See next slides

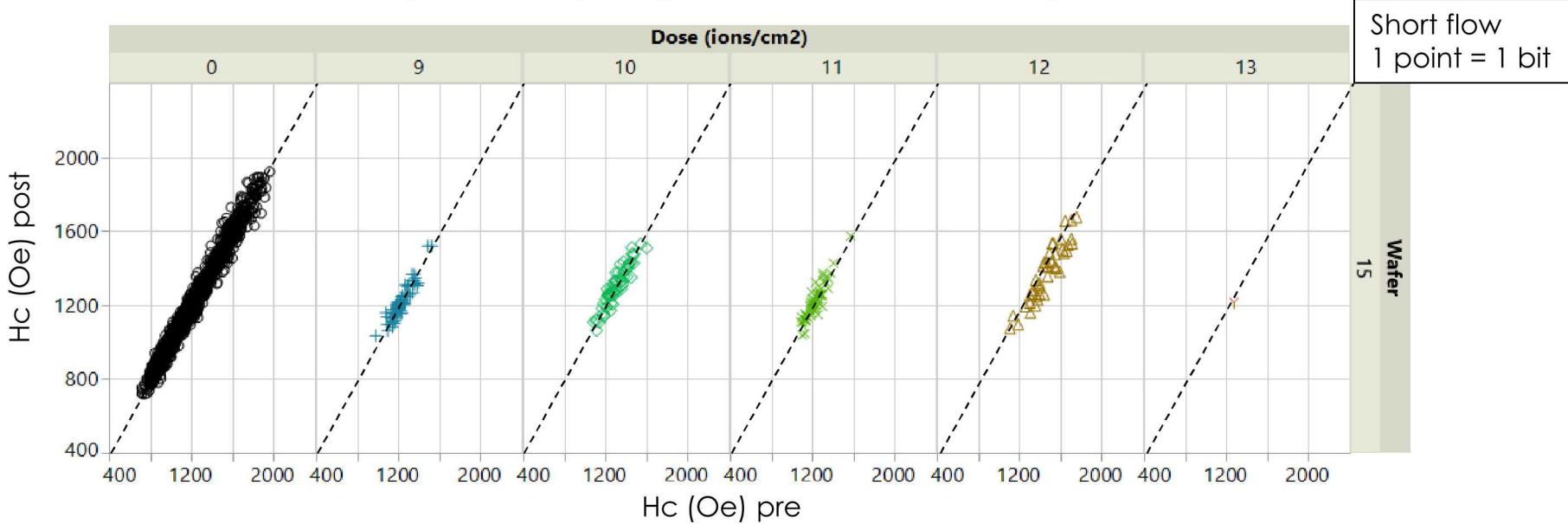
MR: Post vs. Pre-Exposure (Single MTJ Structures)

Short flow
1 point = 1 bit



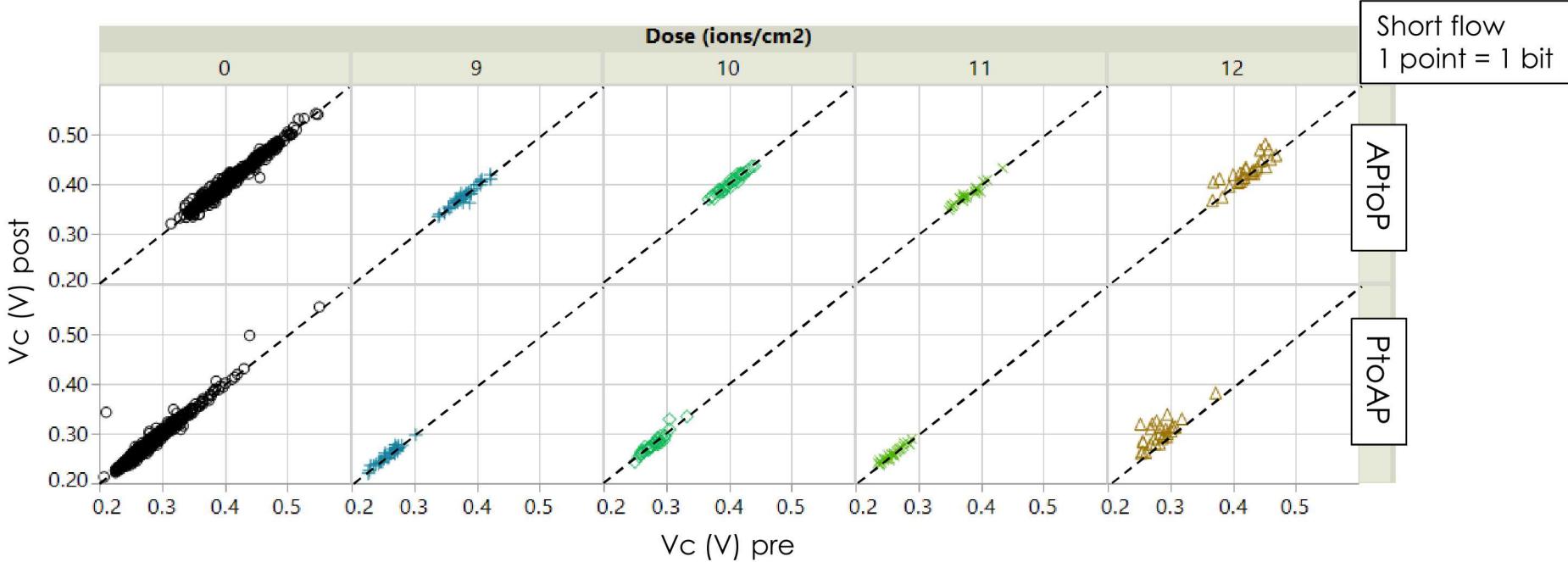
- MR is almost unchanged by exposure up to 10^{11} ions/cm²
- Mild MR decrease at 10^{12} ions/cm² indicates some effect
- Loss of MR at $10^{13} - 10^{14}$ ions/cm² indicates more significant damage

Hc: Post vs. Pre-Exposure (Single MTJ Structures)



- Hc is unchanged by exposure up to 10^{11} ions/cm²
- Mild Hc decrease at 10^{12} ions/cm² indicates some effect
- No data plotted at 10^{13} – 10^{14} ions/cm² because they have no MR so Hc cannot be defined
- Hc-correlation plots are noisier than for Rmin and MR due to thermal-activated, random switching in MTJs: This is inherent to MTJs and seen also at dose = 0

Vc: Post vs. Pre-Exposure (Single MTJ Structures)



- Vc is unchanged by exposure up to 10^{11} ions/cm²
- 10^{12} ions/cm²: Slight increase in magnitude and spread of Vc
- No data plotted at 10^{13} – 10^{14} ions/cm² because they have no MR, so Vc cannot be defined

Summary

- Everspin has successfully transitioned STT-MRAM from R&D to volume manufacturing
 - 256Mb and 1Gb in production at Everspin
 - R&D roadmap to higher densities planned
- Examined magnetic field and spin torque voltage switching before/after heavy ion exposure
 - Negligible changes up to dose of 10^{12} ions/cm²
 - 10^{13} - 10^{14} ions/cm² significantly affect MTJ behavior
- No significant change after exposure up to dose of 10^{12} ions/cm² for:
 - Magnetic-field switching: Rmin, MR, and Hc
 - Spin-torque voltage switching: Vc

Acknowledgements

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 - H. Almasi, M. DeHerrera, B. Hughes, S. Ikegawa, J. Janesky, H. K. Lee, H. Lu, F.B. Mancoff, K. Nagel, G. Shimon, J.J. Sun, T. Andre, S. M. Alam

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Thank you.



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